Specifications

Drawing No.	UKY1C-H1-16640-00[43] 1/11
Issued Date.	Jul,5,2016

TO:	KED		

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Quartz Crystal
Product Model	CX3225SB
Frequency	16000kHz
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	CX3225SB16000D0GZJC1
Remarks Pb-Free, RoHS Comp	bliant, MSL 1

Customer Acceptance

Accept Signature	Approved Date	
	Department	
	Person in charge	

Seller KYOCERA Crystal Device Corporation

(Sales Division)

6 Takeda Tobadono-cho, Fushimi-ku, Kyoto

612-8501 Japan

TEL. No. 075-604-3500 FAX. No. 075-604-3501

Manufacturer

Crystal Units Division 5850, Higashine-Koh, Higashine-Shi, Yamagata 999-3701 Japan TEL. No. 0237-43-5611

FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Crystal Units Engineering Section Crystal Units Division	T. Noritake	H. Shoji	T. Nitoube	Y. Kikuchi

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Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
1	First Edition	Jul,5,2016	H. Shoji	T. Nitoube	Y. Kikuchi

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1. APPLICATION

This specification sheet is applied to quartz crystal "CX3225SB16000D0GZJC1"

2. KYOCERA PART NUMBER

CX3225SB16000D0GZJC1

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-10 to +75	°C	
Storage Temperature range	Tstg	-40 to +85	°C	

4. CHARACTERISTICS

ELECTRICAL CHARACTERISTICS

Items		Electrical Specification			Test Condition	Remarks	
	SYMB.	Min	Тур.	Max	Unit		
Mode of Vibration			Fundamenta				
Nominal Frequency	F0		16		MHz		
Nominal Temperature	T _{NOM}		+25		°C		
Load Capacitance	CL		8.0		pF		
Frequency Tolerance	df/F	-15.0		+15.0		+25±3°C	
Frequency Temperature characteristics	df/F	-15.0		+15.0	PPM	-10 to +75°C	
Frequency Aging Rate		-1.0		+1.0		1 st year	+25±3°C
Equivalent Series Resistance	ESR			60	Ω		
Drive Level	Pd	0.01		100	μW		
Insulation Resistance	IR	500			ΜΩ	100V(DC)	

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5. Measurement Condition

5.1 Frequency measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : 8.0pF Drive Level : 10µW

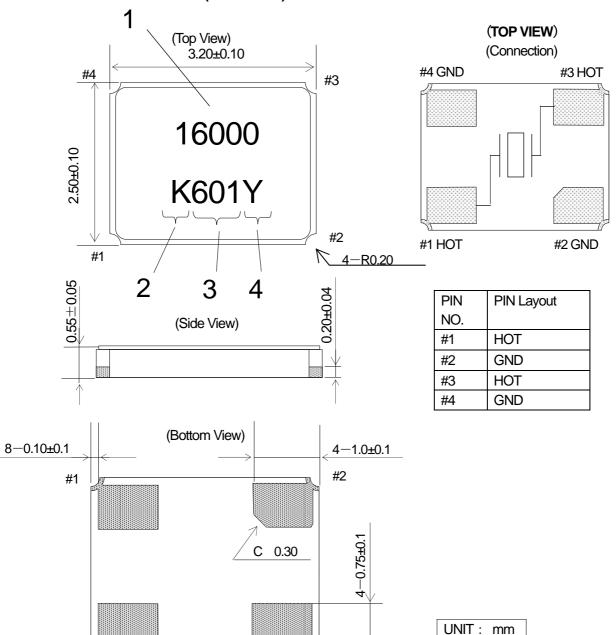
5.2 Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series
Drive Level : 10µW

Drawing No.

6. APPEARANCES, PHYSICAL DIMENSION **OUTLINE DIMENSION (not to scale)**



- #4 MARKING Nominal Frequency Move the number of maximum indication beams of the
- 2 Identification [K] mark is surely 1Pin direction.
- 3 Date Code Year···LAST 1 DIGIT of YEAR AND WEEK

(Ex)Jan, 01, 2016 \rightarrow 601

Manufacturing Location

Y···Japan(Yamagata) Z···Japan(Shiga Yohkaichi)

T···Thailand

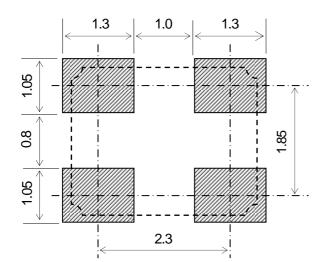
%The font of marking is reference.

#3

frequency to five digits, and omit less than kHz.

KYOCERA Crystal Device Corporation

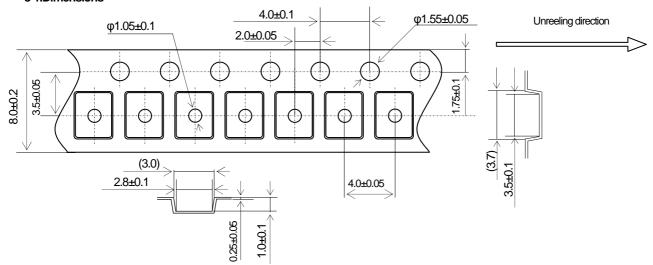
7. RECOMMENDED LAND PATTERN (not to scale)



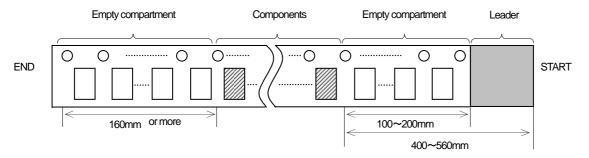
UNIT: mm

8.TAPING & REEL

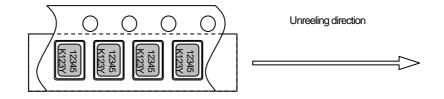
8-1.Dimensions



8-2.Leader and trailer tape

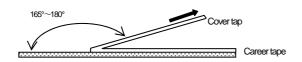


8-3. Direction (The direction shall be seen from the top cover tape side)

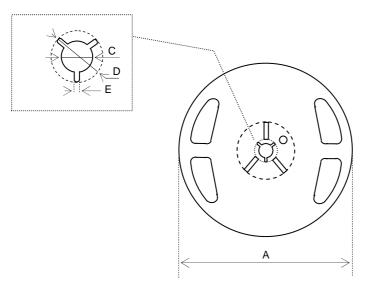


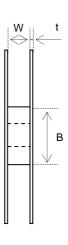
8-4. Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the comer of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 8-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.



8-5.Reel Specification





In the case of Φ180 Reel (3,000 pcs max, every 1,000 pcs)

Symbol	Α	В	С	D
Dimension	φ 180 + 0/-3	φ 60 + 1/-0	φ 13±0.2	φ 21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9±1	2.0±0.5	

(Unit: mm)

In the case of Φ330 Reel (10,000 pcs max, every 1,000 pcs)

Symbol	Α	В	С	D
Dimension	φ 330±2.0	φ 100±1.0	φ 13±0.2	φ 21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9.5±0.5	2.2±0.1	

(Unit: mm)

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9. Environmental requirements

After following test, frequency shall not change more than $\pm 10 \times 10^{-6}$ And CI, $\pm 20\%$ or 5Ω of large value.

9.1 Resistance to Shock Test condition

Natural dropped from height 100cm onto hard wood

board in 3 times

9.2 Resistance to Vibration Test condition

frequency : 10 - 55 - 10 Hz

Amplitude : 1.5mm

Cycle time : 15 minutes

Direction : X,Y,Z (3direction),2 h each.

9.3 Resistance to Heat Test condition

The quartz crystal unit shall be stored at a temperature of $+85\pm2^{\circ}\text{C}$ for 500 h.

Then it shall be subjected to standard atmospheric conditions for 1 h ,after whichi measurement shall

be made.

9.4 Resistance to Cold Test condition

The quartz crystal unit shall be stored at a

temperature of -40 \pm 2°C for 500 h.

Then it shall be subjected to standard atmospheric conditions for 1 h ,after whichi measurement shall

be made.

9.5 Thermal Shock Test condition

The quartz crystal unit shall be subjected to 500 succesive change of temperature cycles, each as shown in table below, Then it shall be subjected to standard atmospheric conditions for 1h, after

which measurements shall be made.

Cycle : $-40\pm2^{\circ}$ C (30min.) to $+25\pm2^{\circ}$ C (5min.)

to +85±2°C (30min.) to +25±2°C (5min.)

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9.6 Resistance to Moisture

Test condition

The quartz crystal unit shall be stored at a temperature of $+60\pm2^{\circ}\text{C}$ wich relative humidity of 90% to 95% for 240 h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made

9.7 Soldering condition

Material of solder

Kind \cdots lead free solder paste Melting point \cdots +220 \pm 5°C

2.) Reflow temp.profile

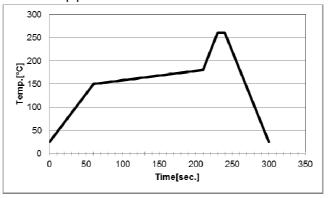
	Temp [°C]	Time[sec]
Preheating	+150 to +180	150 (typ.)
Peak	+260±5	10 (max.)
Total		300 (max.)

Frequency shift : ±2ppm

3.) Hand Soldering +350°C 3 sec MAX

4.) Reflow Times 2 times

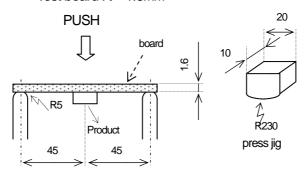
Reflow temp.profile



9.8 Intensity for bending in circuit board

Solder this product in center of the circuit board of $40 \text{mm} \times 100 \text{mm}$, and add the deflection of 3mm as the bottom figure.

Test board: t=1.6mm



UNIT: mm

10. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

(2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 5 times the ESR (Equivalent Series Resistance) of crystal unit.

11. Storage conditions

Please store product in below conditions, and use within 6 months.

Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

12. Manufacturing location

Kyocera Crystal Device Corporation / Japan(Yamagata)

Kyocera Crystal Device Corporation Shiga Yohkaichi Plant / Japan(Shiga)

Kyocera Crystal Device (Thailand) Co., Ltd / Thailand(Lamphun)

13. Quality Assurance

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

14. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1 year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1 year of its delivery is waivered.

15. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.